ABSTRACT

It is an object of the present invention to provide a fine surface treatment for micromachining having etching speed whose difference is smaller to oxide films each obtained by a different method as well as conditions of forming film or having different concentration of various impurities such as P, B and As in the film, and also having practical etching speed to each of the films.

The surface treatment for micromachining contains 0. 1 to 8 weight % of hydrogen fluoride and not less than 40 weight % to not more than 47 weight % of ammonium fluoride. It should be noted that it is preferable the agent contains 0. 001 to 1 weight % of surfactant.

FIGURE 2